

**In The Claims**

Please enter new claims 40 and 41 as follows.

1. (Currently amended) A material comprising ~~elements of~~ Si, C, O and H, said composition having a non-polymeric, covalently bonded structure comprising Si-C, Si-H, Si-O and C-H bonds and a dielectric constant of not more than 3.6.

2. - 39. (Cancelled)

40. (NEW) A material comprising Si, C, O and H, said composition having a non-polymeric, covalently bonded structure comprising Si-C, Si-H, Si-O and C-H bonds and a dielectric constant of not more than 3.6, said composition further comprises between about 5 and about 40 atomic percent of Si; between about 5 and about 45 atomic percent of C; between 0 and about 50 atomic percent of O; and between about 10 and about 55 atomic percent of H, said composition further comprises at least one element selected from the group consisting of F, N, and Ge.

41. (NEW) A material composition comprising elements of Si, C and H, said composition having a non-polymeric covalently

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bonded ring network comprising Si-C, Si-H and C-H bonds and a dielectric constant of not more than 3.6.

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The Commissioner is hereby authorized to charge the fee required for these additional claims and any other fee as required to Deposit Account No. 50-0510.

Respectfully submitted,

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